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EPOXY DC-202

Low to medium flow, highly cross-linked epoxy system.

Designed for sealing PCB components.

Holds up well to industrial solvent exposure and soldering temperatures up to 325°C.

Capable of UL94HB flammability rating.

| RECOMMENDED CURE SCHEDULES FOR DC-202 | | |
|---|--|--------------------------------|
| 212°F (100°C) for 4 hours minimum | | |
| 250°F (125°C) for 1 hour minimum | | |
| 300°F (150°C) for 30 minutes minimum | | |
| 350°F (175°C) for 15 minutes minimum | | |
| CURE METHOD: We recommend the use of forced convection ovens for curing our epoxy systems. When using static air ovens, recommended cure times should be doubled. Recommended cure schedules are for epoxy only. Place thermocouples throughout the oven to determine the influence of component mass on oven temperature and recovery time. Please refer to "Uni-form Epoxies Recommendations" bulletin for additional curing instructions. | | |
| SPECIFICATIONS | | |
| ASTM D257 | Volume Resistivity (ohms/inch) | $1.0 \times 10^{12} - 10^{14}$ |
| ASTM D570 | Water Absorption (weight %) | 0.80 max. |
| ASTM D696 | Coefficient Thermal Expansion (in/in °C) | 5.0 - 7.0 x10 ⁻⁵ |
| ASTM D955 | Shrinkage from Mold (inches/inch) | 0.1 - 0.3 x10 ⁻² |
| ASTM D2240 | Durometer Hardness (Shore D) | 80-85 |
| ASTM D149 | Dielectric Strength (60 Hz, volts/mil) | 800 min. |
| DSC METHOD | Thermal Conductivity (cal cm/sec cm ² · °C) | 4.0 - 6.0 x10 ⁻⁴ |

PLEASE NOTE: This information is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished up the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

Form: MK-017 Rev. A 1/11/01